DRA2L14Y

Silicon PNP epitaxial planar type

For digital circuits

■ Features

- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	-30	V
Collector-emitter voltage (Base open)	V _{CEO}	-30	V
Collector current	I_{C}	-100	mA
Total power dissipation	P _T	200	mW
Junction temperature	T_j	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

■ Package

• Code

Mini3-G3-B

- Pin Name
 - 1: Base
 - 2: Emitter
 - 3: Collector

■ Marking Symbol: K4

■ Internal Connection

$$B \circ \overbrace{R_2}^{R_1} \circ C$$

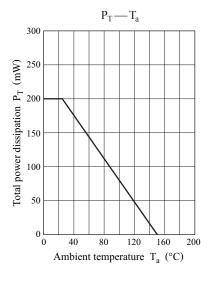
Resistance	R ₁	10	kΩ
value	R ₂	47	kΩ

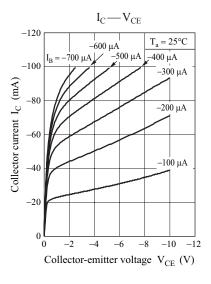
■ Electrical Characteristics $T_a = 25$ °C±3°C

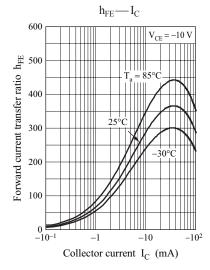
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \mu A, I_{\rm E} = 0$	-30			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-30			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{\rm CB} = -30 \text{ V}, I_{\rm E} = 0$			-0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -30 \text{ V}, I_{B} = 0$			-0.5	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -3 \text{ V}, I_{C} = 0$			-0.1	mA
Forward current transfer ratio	h _{FE}	$V_{CE} = -10 \text{ V}, I_{C} = -5 \text{ mA}$	80			_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -50 \text{ mA}, I_B = -0.33 \text{ mA}$		-0.6	-1.2	V
Input voltage (ON)	V _{I(on)}	$V_{CE} = -0.2 \text{ V}, I_{C} = -5 \text{ mA}$	-1.5			V
Input voltage (OFF)	V _{I(off)}	$V_{CE} = -5 \text{ V}, I_{C} = -100 \mu\text{A}$			-0.5	V
Input resistance	R_1		-30%	10	+30%	kΩ
Resistance ratio	R_1/R_2		0.16	0.213	0.27	

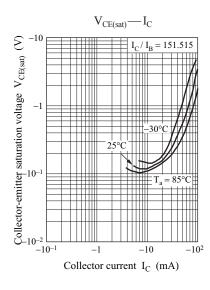
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

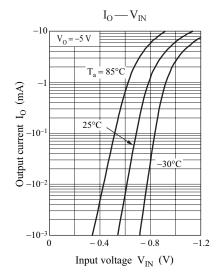
DRA2L14Y Panasonic

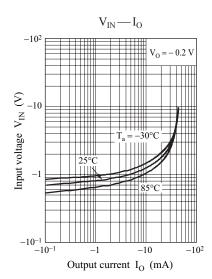






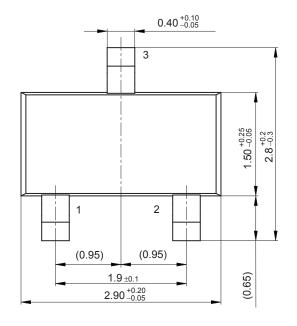


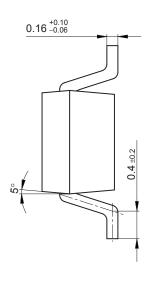


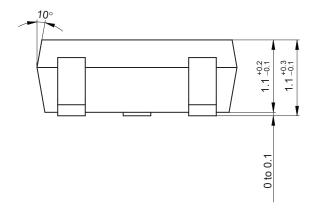


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Mini3-G3-B Unit: mm







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